

IN THE CLAIMS:

1. (Currently Amended) A semiconductor integrated circuit comprising:

pads on a surface of a semiconductor substrate, and

a plurality of wirings electrically connected to the pads,

wherein said wirings are located for contacting bumps on a probe card, when such a card is located parallel to said surface of the semiconductor substrate and contiguous to said wirings, but spaced from said pads.

2. (Previously Presented) A semiconductor integrated circuit as defined in Claim 1

comprising at least two of said wirings, both of which physically contact one of said bumps, without touching each other.

3. (Previously Presented) A semiconductor integrated circuit as defined in Claim 2

wherein each of said wirings has at least one bent portion or angular portion for directly contacting one or more bumps.

4. (Currently Amended) A semiconductor integrated circuit as defined in Claim 2 wherein said

wirings have electrically separable portions for electrically disconnecting said wirings from said pads.